

**REMARKS**

Applicants appreciate the Examiner's thorough review of the present application, and respectfully request reconsideration in light of the preceding amendments and the following remarks.

Claims 4-7 and 11-22 are pending in the application. Original claims 4-7 and 11-14 have not been amended notwithstanding the art rejection manifested in the Office Action. Claims 15-22 have been added to provide Applicants with the scope of protection to which they are believed entitled. No new matter has been introduced through the foregoing amendments.

The 35 U.S.C. 102(e) rejection of claims 4-7 and 11-14 as being anticipated by Jung et al. (U.S. Patent No. 6,342,730) is traversed because the Examiner fails to demonstrate how Jung teaches or discloses each and every element of the rejected claims.

Independent claims 4 and 11 are directed to low-pin-count chip packages comprising a semiconductor chip and a plurality of connection pads electrically coupled to the chip. A package body is formed over the semiconductor chip and the connection pads using known plastic molding methods such as transfer molding. Claims 4 and 11 specifically require that each connection pad have a portion *extending outward* from the bottom of the package body. The extension portions of the connection pads facilitate surface mounting of the package to a substrate.

The language of the Office Action does not specifically indicate how the above feature and advantage are disclosed, taught, or even suggested by Jung. Page 3 lines 1-3 of the Office Action is deemed inaccurate because connection pads 230 in Figs. 2 and 10 of Jung are illustrated to have lower surfaces which are *flush* with the bottom of package body 220.

In addition, the Examiner fails to demonstrate how the limitations of claims 7 and 14 are met by Jung. Namely, claims 7 and 14 recite that areas on the surfaces of each connection pad

without protection of the package body have a *third metal coating* formed thereon thereby avoiding corrosion and contamination (see also page 6, lines 28-31 of the specification and Fig. 16). The Examiner's reliance on column 5, line 5 for this claim feature is apparently misplaced, as the Examiner takes column 5, line 5 out of the whole context of the Jung patent.

Accordingly, Applicants respectfully submit that the anticipatory rejection of claims 4-7 and 11-14 is not well grounded and should be withdrawn.

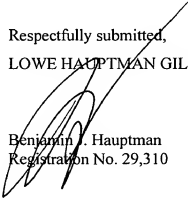
New claims 15-22 are patentable as will be apparent to the Examiner upon reviewing same.

Each of the Examiner's rejections has been traversed. Accordingly, Applicants respectfully submit that all claims are now in condition for allowance. Early and favorable indication of allowance is courteously solicited.

The Examiner is invited to telephone the undersigned, Applicant's attorney of record, to facilitate advancement of the present application.

Respectfully submitted,

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Date: September 9, 2002  
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